

**ABSTRACT**

A solid-state imaging apparatuses IS1 comprises a package P1, a CCD chip 11, chip resistor arrays 21, etc. In package P1, a mounting portion 2, for mounting CCD chip 11 and chip resistor arrays 21, is disposed so as to protrude into a hollow portion 1. Mounting portion 2 has a first planar portion 3 and second planar portions 4, and first planar portion 3 and second planar portions 4 are formed to be stepped with respect to each other. CCD chip 11 is mounted and fixed on first planar portion 3 via a spacer 13. Chip resistor arrays 21 are mounted and fixed on second planar portions 4. Using the step difference between first planar portion 3 and second planar portions 4, CCD chip 11 and chip resistor arrays 21 are positioned proximally.